



Hexa EVO+

2D and 3D High Speed Scanner

The Hexa EVO+ provides the most comprehensive quality assurance solution for detection of backend process induced defects for all ball array, peripheral leaded/ leadless and large form factor packages.

The highly modular design concept allows flexibility for various options like dual taper, auxiliary tray input, top and bottom surface inspection, side surface inspection etc. Simple and repeatable conversions also make the Hexa EVO+ perfectly suited for customers with high mix, small lot size production environment.

With STI's proprietary vision solution and advanced automation features, the Hexa EVO+ offers a diverse menu of inspection and output options configurable to match all package requirements.



Features:

- Large Package Inspection Capability up to 100mm
- Multi-Row Scanning
- Throughput up to 90,000 uph
- Scan-Pack Option with Dual Taping Output
- Powerful Auto Teach Algorithm
- Automated Accuracy Check
- Orientation Corrector
- Reject Management
- Telecentric Lens

Obsessed with Inspection:

- Top & Bottom 3D Inspection
- True Ball Height
- Flexible Pad Inspection
- Package Visual Inspection
- Image / Fingerprint Sensor Inspection
- Side-Surface Inspection
- In-Pocket Inspection
- Colour Inspection
- Package Thickness Measurement
- Micro Crack Inspection
- True Mold Thickness Measurement